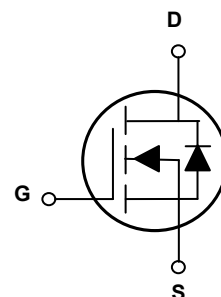


Main Product Characteristics

BV_{DSS}	30V
$R_{DS(ON)}$	1.4mΩ
I_D	240A



PPAK5x6



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFP3990 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	+20/-12	V
Drain Current-Continuous ($T_C=25^{\circ}\text{C}$)	I_D	240	A
Drain Current-Continuous ($T_C=100^{\circ}\text{C}$)		150	
Drain Current-Pulsed ¹	I_{DM}	960	A
Single Pulse Avalanche Energy ²	E_{AS}	540	mJ
Single Pulse Avalanche Current ²	I_{AS}	104	A
Power Dissipation ($T_C=25^{\circ}\text{C}$)	P_D	178	W
Power Dissipation-De-rate above 25°C		1.43	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.7	$^{\circ}\text{C/W}$
Operating Junction Temperature Range	T_J	-55 To +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 To +150	$^{\circ}\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	-	-	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =20V, V _{DS} =0V	-	-	100	nA
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =30A	-	1.2	1.4	mΩ
		V _{GS} =4.5V, I _D =15A	-	1.8	2.3	
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	1	1.6	2.5	V
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =3A	-	15	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q _g	V _{DS} =15V, I _D =80A V _{GS} =10V	-	73	110	nC
Gate-Source Charge ^{3,4}	Q _{gs}		-	15	25	
Gate-Drain Charge ^{3,4}	Q _{gd}		-	12	20	
Turn-On Delay Time ^{3,4}	t _{d(on)}	V _{DD} =15V, R _G =6Ω V _{GS} =10V, I _D =80A	-	20	30	nS
Rise Time ^{3,4}	t _r		-	15	25	
Turn-Off Delay Time ^{3,4}	t _{d(off)}		-	30	45	
Fall Time ^{3,4}	t _f		-	25	40	
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, F=1MHz	-	5090	7650	pF
Output Capacitance	C _{oss}		-	2050	3100	
Reverse Transfer Capacitance	C _{rss}		-	85	130	
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	1.5	-	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	-	-	240	A
Pulsed Source Current	I _{SM}		-	-	480	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25°C	-	-	1	V
Reverse Recovery Time	t _{rr}	V _R =30V, I _S =10A di/dt=100A/μs T _J =25°C	-	150	-	nS
Reverse Recovery Charge	Q _{rr}		-	300	-	nC

Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=104A, R_G=25Ω, starting T_J=25°C.
3. Pulse test: pulse width ≤300us, duty cycle ≤2%.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

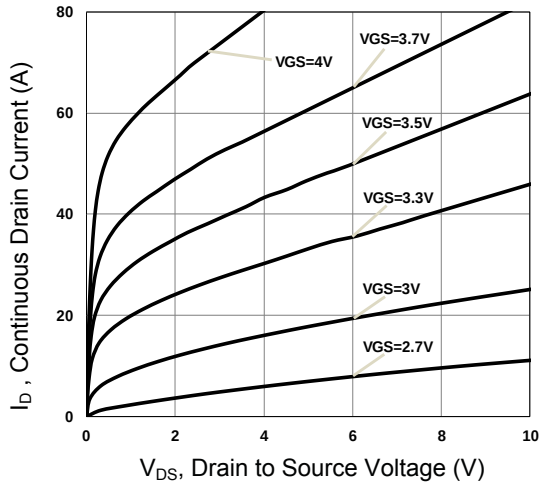


Figure 1. Typical Output Characteristics

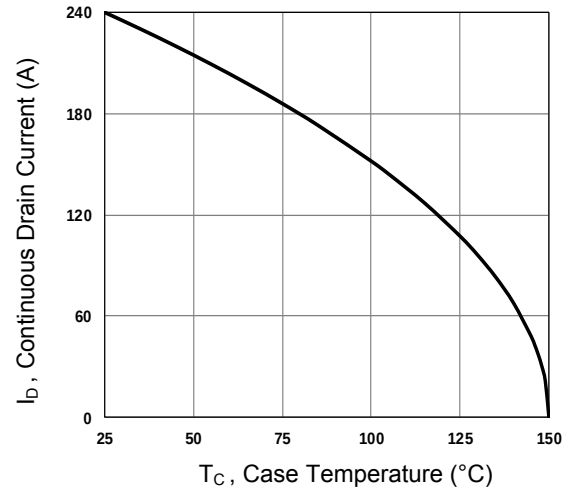


Figure 2. Continuous Drain Current vs. T_C

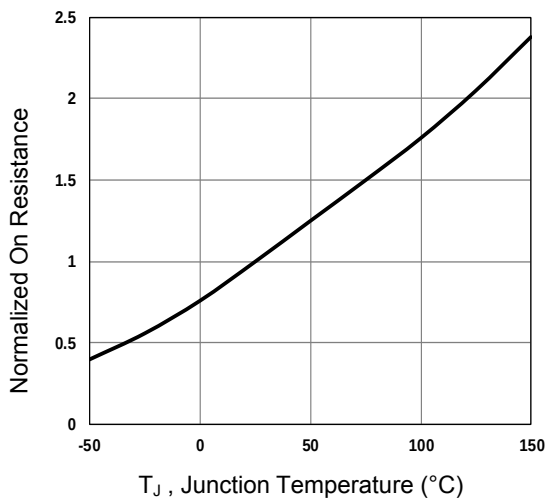


Figure 3. Normalized $R_{DS(on)}$ vs. T_J

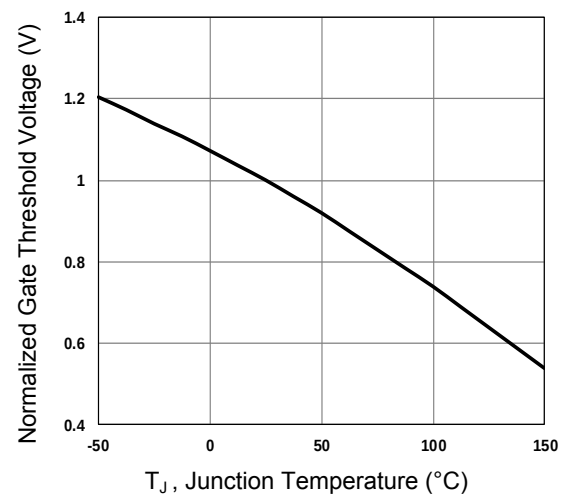


Figure 4. Normalized V_{th} vs. T_J

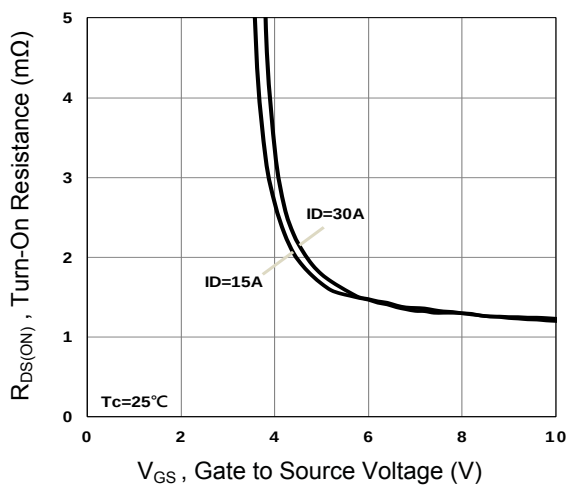


Figure 5. Turn-On Resistance vs. V_{GS}

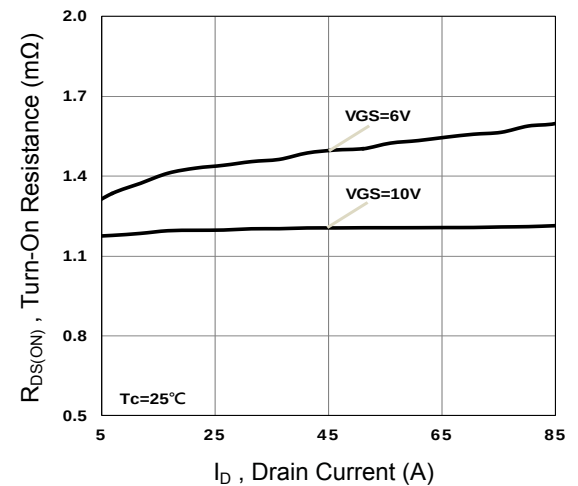


Figure 6. Turn-On Resistance vs. I_D

Typical Electrical and Thermal Characteristic Curves

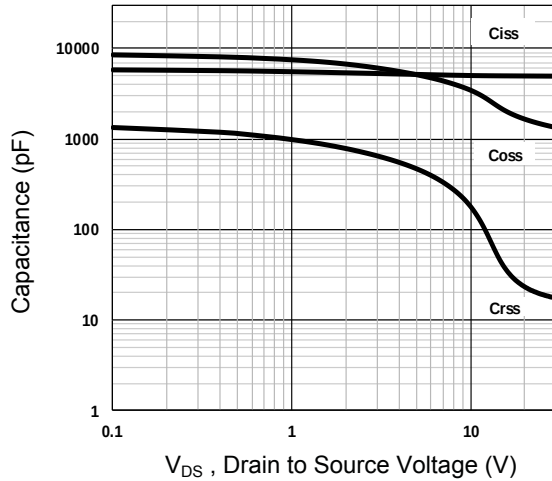


Figure 7. Capacitance Characteristics

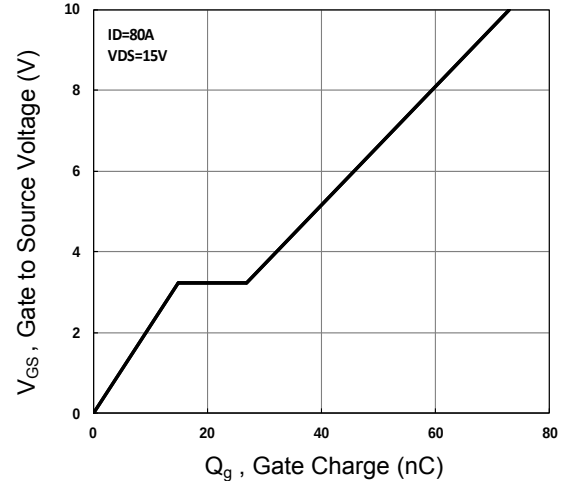


Figure 8. Gate Charge Characteristics

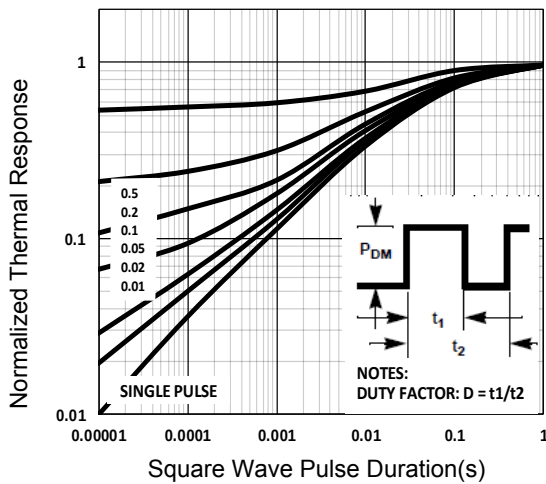


Figure 9. Normalized Transient Impedance

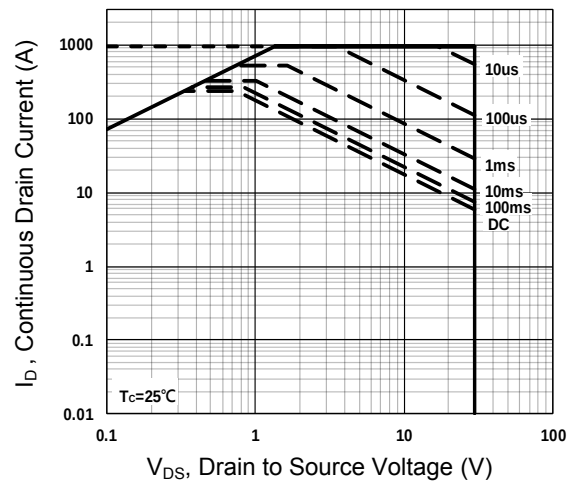


Figure 10. Maximum Safe Operation Area

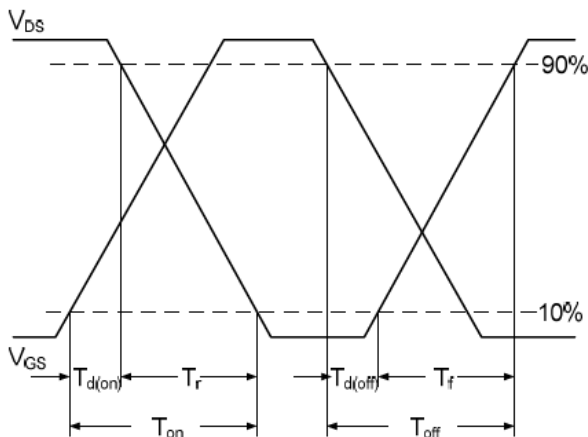


Figure 11. Switching Time Waveform

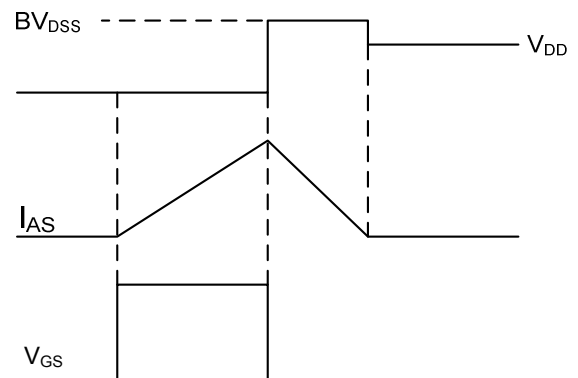
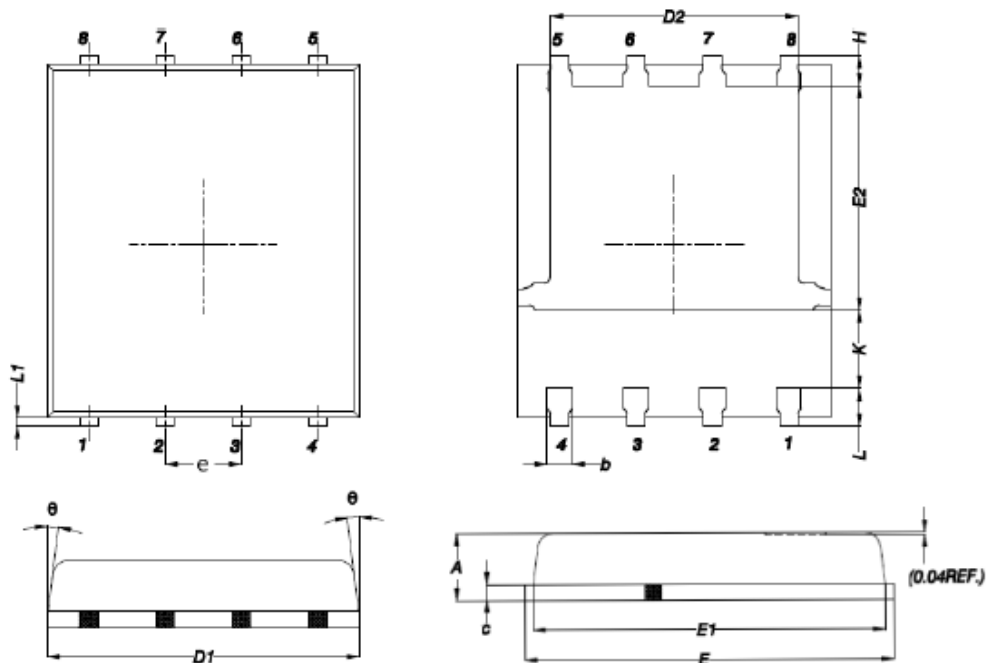


Figure 12. EAS Waveform

Package Outline Dimensions

PPAK5x6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	-	1.100	-	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°